



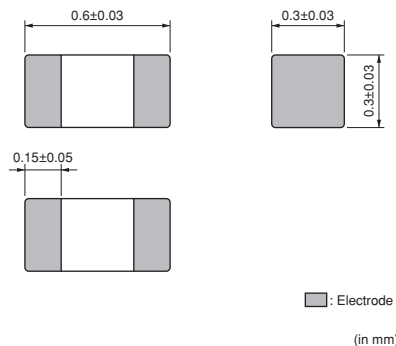
**THE DATASHEET OF
BLM03EB500SN1D**



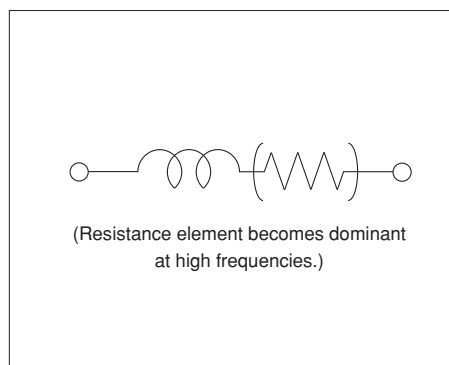
EMIFIL® (Inductor type) Chip Ferrite Bead for GHz Noise

BLM03E Series (0201 Size)

■ Dimensions



■ Equivalent Circuit



■ Packaging

Code	Packaging	Minimum Quantity
D	180mm Paper Tape	15000
J	330mm Paper Tape	50000
B	Bulk(Bag)	1000

■ Rated Value (□: packaging code)

Part Number	Impedance (at 100MHz/20°C)	Impedance (at 1GHz/20°C)	Rated Current	DC Resistance	Operating Temperature Range
BLM03EB250SN1□	25ohm ±25%	105ohm ±40%	600mA	0.26ohm max.	-55 to +125°C
BLM03EB500SN1□	50ohm ±25%	255ohm ±40%	400mA	0.58ohm max.	-55 to +125°C

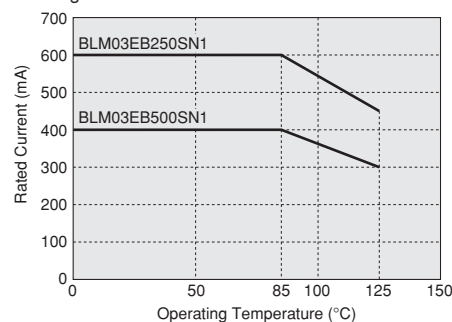
Number of Circuits: 1

■ Derating of Rated Current

In operating temperature exceeding +85°C, derating of current is necessary for BLM03E series.

Please apply the derating curve shown in chart according to the operating temperature.

Derating of Rated Current




Continued on the following page.

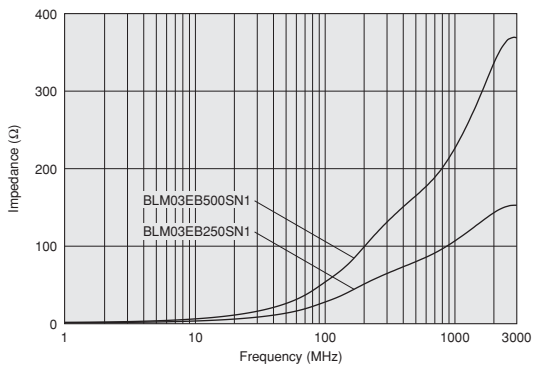
● This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

⚠ Note:

- This datasheet is downloaded from the website of Murata Manufacturing co., ltd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.
- This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.

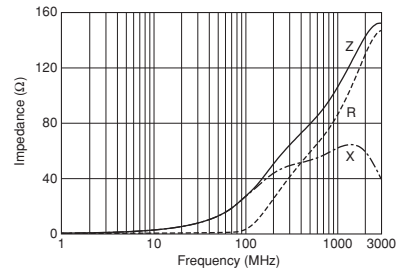
 Continued from the preceding page.

■ Impedance-Frequency Characteristics (Main Items)



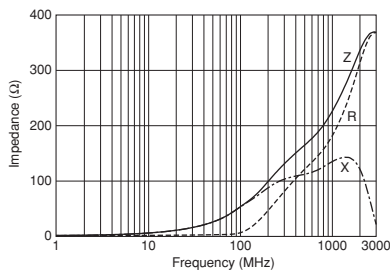
■ Impedance-Frequency Characteristics

BLM03EB250SN1



■ Impedance-Frequency Characteristics

BLM03EB500SN1



■ ⚠ Caution/Notice

⚠ Caution (Rating)

Do not use products beyond the rated current as this may create excessive heat and deteriorate the insulation resistance.

Notice

Solderability of Tin plating termination chip might be deteriorated when low temperature soldering profile where peak solder temperature is below the Tin melting point is used. Please confirm the solderability of Tin plating termination chip before use.

● This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

⚠ Note:

1. This datasheet is downloaded from the website of Murata Manufacturing co., ltd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.
2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

- ⊖ [View BLM03EB500SN1D on WIN SOURCE](#)
- ⊖ [Murata Electronics North America Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

- ✓ Global Sourcing Solution
- ✓ Obsolete Management
- ✓ Cost Control Management
- ✓ Shortage Management
- ✓ Alternative Solution
- ✓ Excess Inventory Management